



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20251105000.1

**Qualification of DFAB as an additional Fab site option for select JIBB devices
Change Notification / Sample Request**

Date: November 05, 2025

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) [process](#)

TI requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 60 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

As referenced in the "reason for change" below, this particular PCN relates to TI's multiyear transition, announced in 2020, to close our 150mm production and move more capacity into 300mm. We are entering the final phases of this transition, and the final 150mm wafers started in October 2025. **Thus, it's critical that you take the appropriate actions, noted in this PCN, to prepare for applicable product changes.**

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

Change Management Team
SC Business Services

20251105000.1
Attachment

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
OPA547T-1	
OPA452FA/500	
INA125UA	
OPA2244EA/2K5	
PGA204AU/1K	
OPA547T	
INA2132UA/2K5	
INA125U	
INA2132UA	
OPA547FKTWT	
OPA2541SM	
INA2132U	
INA163UA	
OPA547F/500	
PGA204BU/1K	
OPA552FA/500	
OPA453TA	
INA125U/2K5	
OPA552FAKTWT	
PGA204AU	
PGA205BU	
OPA2244EA/2K5	
OPA549T	
OPA244NA/3K	
OPA452FAKTWT	
OPA2544T	
OPA445AU/2K5	
INA2143U	
INA125U/2K5	
INA125UA/2K5	
OPA552FAKTWT	
INA217AIDWR	
INA143UA/2K5	
OPA541AP	
OPA2541SMQ	
INA163UA/2K5	
INA2132UA/2K5	
OPA552FA/500	
PGA205AU	
INA2143UA	
OPA541AP	
OPA2541SM	
INA163UA/2K5	
INA143U/2K5	
OPA552UA/2K5	
INA163UA	
INA217AIDWT	
OPA2244UA/2K5	
INA143UA/2K5	
OPA453FAKTWT	
OPA549S	

INA2132UA	
OPA2541SMQ	
OPA445AP	
OPA541BM	
OPA552UA	
OPA244UA/2K5	
PGA204BU	
PGA205AU/1K	
OPA541SM	
INA2132U/2K5	
OPA445AU	
OPA2244UA/2K5	
LOG112AID	
OPA547F/500	

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251105000.1	PCN Date:	November 05, 2025																		
Title:	Qualification of DFAB as an additional Fab site option for select JIBB devices																				
Customer Contact:	Change Management Team	Dept:	Quality Services																		
Proposed 1st Ship Date:	February 03, 2026	Sample requests accepted until:	January 04, 2026*																		
*Sample requests received after January 04, 2026 will not be supported.																					
Change Type:																					
☐ Assembly Site	☐ Design	☐ Wafer Bump Material																			
☐ Assembly Process	☐ Data Sheet	☐ Wafer Bump Process																			
☐ Assembly Materials	☐ Part number change	☒ Wafer Fab Site																			
☐ Mechanical Specification	☐ Test Site	☒ Wafer Fab Material																			
☐ Packing/Shipping/Labeling	☐ Test Process	☐ Wafer Fab Process																			
PCN Details																					
Description of Change:																					
Texas Instruments is pleased to announce the addition of DFAB as an additional Wafer Fab option for the devices listed below.																					
<table border="1"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">Additional Fab Site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Additional Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>SFAB</td> <td>JIBB</td> <td>150 mm</td> <td>DFAB</td> <td>JIBB</td> <td>200 mm</td> </tr> </tbody> </table>				Current Fab Site			Additional Fab Site			Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter	SFAB	JIBB	150 mm	DFAB	JIBB	200 mm
Current Fab Site			Additional Fab Site																		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter																
SFAB	JIBB	150 mm	DFAB	JIBB	200 mm																
Qual details are provided in the Qual Data Section.																					
Reason for Change:																					
These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.																					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																					
None																					
Changes to product identification resulting from this PCN:																					
Fab Site Information:																					
<table border="1"> <thead> <tr> <th>Chip Site</th> <th>Chip Site Origin Code (20L)</th> <th>Chip Site Country Code (21L)</th> <th>Chip Site City</th> </tr> </thead> <tbody> <tr> <td>SH-BIP-1</td> <td>SHE</td> <td>USA</td> <td>Sherman</td> </tr> <tr> <td>DL-LIN</td> <td>DLN</td> <td>USA</td> <td>Dallas</td> </tr> </tbody> </table>				Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City	SH-BIP-1	SHE	USA	Sherman	DL-LIN	DLN	USA	Dallas						
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City																		
SH-BIP-1	SHE	USA	Sherman																		
DL-LIN	DLN	USA	Dallas																		
Sample product shipping label (not actual product label):																					
TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20: MSL '2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750 (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 8633317 (20L) CS0: SHE (21L) CCO: USA (22L) AS0: MLA (23L) ACO: MYS																					
Product Affected:																					

INA125U	INA217AIDWR	OPA445AU/2K5	OPA549S
INA125U/2K5	INA217AIDWT	OPA452FA/500	OPA549T
INA125UA	LOG112AID	OPA452FAKTWT	OPA552FA/500
INA125UA/2K5	LOG112AIDR	OPA453FAKTWT	OPA552FAKTWT
INA143U/2K5	OPA2244EA/2K5	OPA453TA	OPA552UA
INA143UA/2K5	OPA2244UA/2K5	OPA453TA-1	OPA552UA/2K5
INA163UA	OPA244NA/3K	OPA541AP	PGA204AU
INA163UA/2K5	OPA244UA/2K5	OPA541BM	PGA204AU/1K
INA2132U	OPA2541BM	OPA541SM	PGA204BU
INA2132U/2K5	OPA2541SM	OPA547F/500	PGA204BU/1K
INA2132UA	OPA2541SMQ	OPA547FKTWT	PGA205AU
INA2132UA/2K5	OPA2544T	OPA547T	PGA205AU/1K
INA2143U	OPA445AP	OPA547T-1	PGA205BU
INA2143UA	OPA445AU		

For alternate parts with similar or improved performance, please visit the product page on [TI.com](http://ti.com)

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: INA168QDBVRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	3/2400/0
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	3/30/0
ESD	E2	ESD CDM	-	1000 Volts	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/6/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	3/90/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device [INA168QDBVRQ1](#) is qualified at MSL1 260C
- Qual Device [INA168QDBVRQ1](#) is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2206-002

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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